

MOSFETs Silicon N-channel MOS (U-MOSVII-H)

# **TK72E08N1**

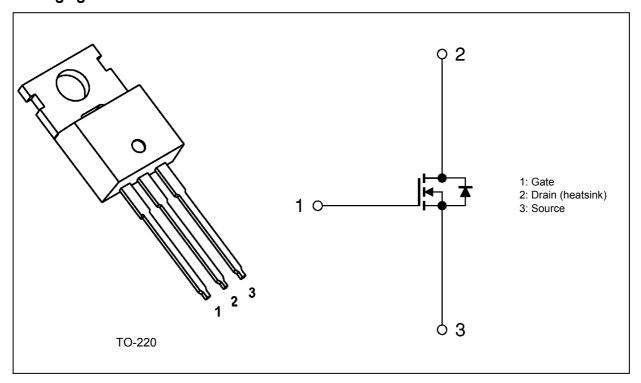
#### 1. Applications

· Switching Voltage Regulators

#### 2. Features

- (1) Low drain-source on-resistance:  $R_{DS(ON)} = 3.6 \text{ m}\Omega$  (typ.) ( $V_{GS} = 10 \text{ V}$ )
- (2) Low leakage current:  $I_{DSS}$  = 10  $\mu A$  (max) ( $V_{DS}$  = 80 V)
- (3) Enhancement mode:  $V_{th}$  = 2.0 to 4.0 V ( $V_{DS}$  = 10 V,  $I_{D}$  = 1.0 mA)

#### 3. Packaging and Internal Circuit





## 4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

| Characteristics               |                         |                    | Symbol           | Rating     | Unit |
|-------------------------------|-------------------------|--------------------|------------------|------------|------|
| Drain-source voltage          |                         |                    | $V_{DSS}$        | 80         | V    |
| Gate-source voltage           |                         |                    | $V_{GSS}$        | ±20        |      |
| Drain current (DC)            | (Silicon limit)         | (Note 1), (Note 2) | I <sub>D</sub>   | 157        | Α    |
| Drain current (DC)            |                         | (Note 1), (Note 3) | Ι <sub>D</sub>   | 72         |      |
| Drain current (pulsed)        | (t = 1 ms)              | (Note 1)           | I <sub>DP</sub>  | 344        |      |
| Power dissipation             | (T <sub>c</sub> = 25°C) |                    | $P_D$            | 192        | W    |
| Single-pulse avalanche energy |                         | (Note 4)           | E <sub>AS</sub>  | 161        | mJ   |
| Avalanche current             |                         |                    | I <sub>AR</sub>  | 72         | Α    |
| Channel temperature           |                         |                    | T <sub>ch</sub>  | 150        | °C   |
| Storage temperature           |                         |                    | T <sub>stg</sub> | -55 to 150 |      |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

| Characteristics                       | Symbol                | Max  | Unit |
|---------------------------------------|-----------------------|------|------|
| Channel-to-case thermal resistance    | R <sub>th(ch-c)</sub> | 0.65 | °C/W |
| Channel-to-ambient thermal resistance | R <sub>th(ch-a)</sub> | 83.3 |      |

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: Limited by silicon chip capability. Package limit is 100 A.

Note 3: Device mounted with heatsink so that R<sub>th(ch-a)</sub> becomes 2.77°C/W.

Note 4:  $V_{DD}$  = 64 V,  $T_{ch}$  = 25°C (initial), L = 24.0  $\mu H,~R_{G}$  = 1.2  $\Omega,~I_{AR}$  = 72 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



#### 6. Electrical Characteristics

## 6.1. Static Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

| Characteristics                         | Symbol               | Test Condition                                    | Min | Тур. | Max  | Unit |
|---|----------------------|---|-----|------|------|------|
| Gate leakage current                    | I <sub>GSS</sub>     | $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ | _   | _    | ±0.1 | μΑ   |
| Drain cut-off current                   | I <sub>DSS</sub>     | V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V     | _   | -    | 10   |      |
| Drain-source breakdown voltage          | V <sub>(BR)DSS</sub> | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V     | 80  | _    | _    | V    |
| Drain-source breakdown voltage (Note 5) | V <sub>(BR)DSX</sub> | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V   | 60  | _    | _    |      |
| Gate threshold voltage                  | V <sub>th</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1.0 mA   | 2.0 | _    | 4.0  |      |
| Drain-source on-resistance              | R <sub>DS(ON)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 36 A     | _   | 3.6  | 4.3  | mΩ   |

Note 5: If a reverse bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.

## 6.2. Dynamic Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

| Characteristics                | Symbol           | Test Condition   | Min | Тур. | Max | Unit |
|--------------------------------|------------------|--|-----|------|-----|------|
| Input capacitance              | C <sub>iss</sub> | V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V, f = 1 MHz | _   | 5500 |     | pF   |
| Reverse transfer capacitance   | C <sub>rss</sub> |  | _   | 38   | _   |      |
| Output capacitance             | C <sub>oss</sub> |  | _   | 1300 | _   |      |
| Gate resistance                | r <sub>g</sub>   | _  | _   | 3.2  |     | Ω    |
| Switching time (rise time)     | t <sub>r</sub>   | See Figure 6.2.1   | _   | 19   | _   | ns   |
| Switching time (turn-on time)  | t <sub>on</sub>  |  | _   | 42   | _   |      |
| Switching time (fall time)     | t <sub>f</sub>   |  | _   | 28   | _   |      |
| Switching time (turn-off time) | t <sub>off</sub> |  | _   | 93   |     |      |

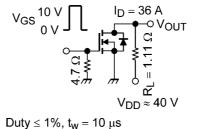


Fig. 6.2.1 Switching Time Test Circuit

## 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

| Characteristics                                 | Symbol           | Test Condition   | Min | Тур. | Max | Unit |
|---|------------------|--|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | $Q_g$            | $V_{DD} \approx 64 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 72 \text{ A}$ | _   | 81   | _   | nC   |
| Gate-source charge 1                            | Q <sub>gs1</sub> |  |     | 29   |     |      |
| Gate-drain charge                               | $Q_{gd}$         |  |     | 21   |     |      |
| Gate switch charge                              | $Q_{SW}$         |  | _   | 33   |     |      |



## 6.4. Source-Drain Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

| Characteristics                |          | Symbol           | Test Condition                                | Min | Тур. | Max  | Unit |
|--------------------------------|----------|------------------|---|-----|------|------|------|
| Reverse drain current (DC)     | (Note 6) | I <sub>DR</sub>  | _   | _   | _    | 72   | Α    |
| Reverse drain current (pulsed) | (Note 6) | I <sub>DRP</sub> | _   | _   | _    | 344  |      |
| Diode forward voltage          |          | V <sub>DSF</sub> | I <sub>DR</sub> = 72 A, V <sub>GS</sub> = 0 V | _   | _    | -1.2 | V    |
| Reverse recovery time          | (Note 7) | t <sub>rr</sub>  | I <sub>DR</sub> = 72 A, V <sub>GS</sub> = 0 V | _   | 77   | _    | ns   |
| Reverse recovery charge        | (Note 7) | Q <sub>rr</sub>  | -dI <sub>DR</sub> /dt = 100 A/μs              | _   | 150  | _    | nC   |

Note 6: Ensure that the channel temperature does not exceed 150°C.

Note 7: Ensure that  $V_{DS}$  peak does not exceed  $V_{DSS}$ .

## 7. Marking

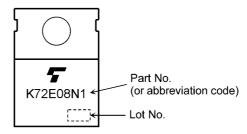


Fig. 7.1 Marking

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#### 8. Characteristics Curves (Note)

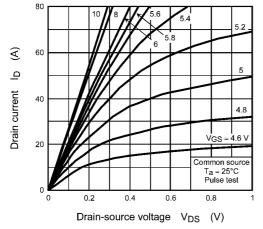
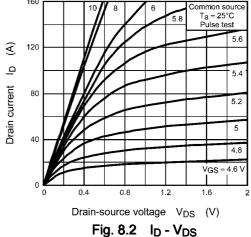


Fig. 8.1  $I_D - V_{DS}$ 



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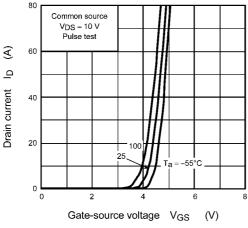


Fig. 8.3 ID - VGS

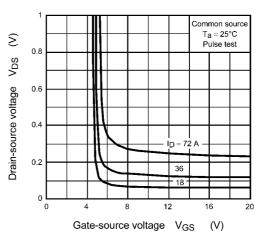


Fig. 8.4 VDS - VGS

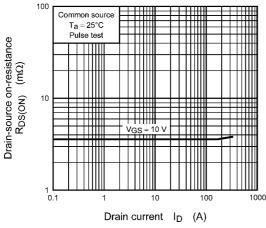


Fig. 8.5 R<sub>DS(ON)</sub> - I<sub>D</sub>

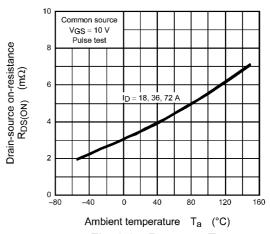


Fig. 8.6 R<sub>DS(ON)</sub> - T<sub>a</sub>

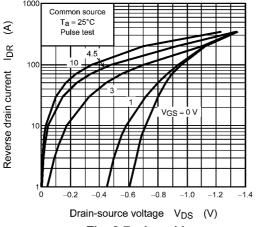


Fig. 8.7 IDR - VDS

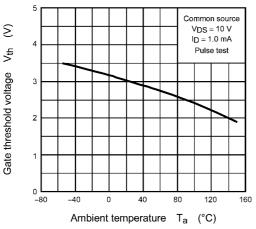


Fig. 8.9 Vth - Ta

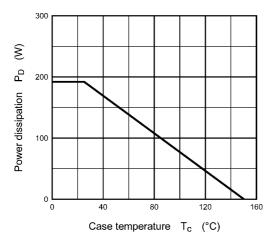


Fig. 8.11 P<sub>D</sub> - T<sub>c</sub> (Guaranteed Maximum)

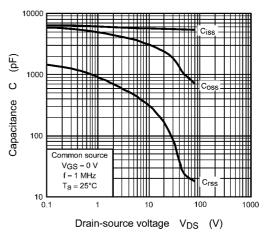


Fig. 8.8 Capacitance - V<sub>DS</sub>

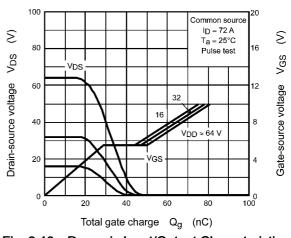


Fig. 8.10 Dynamic Input/Output Characteristics

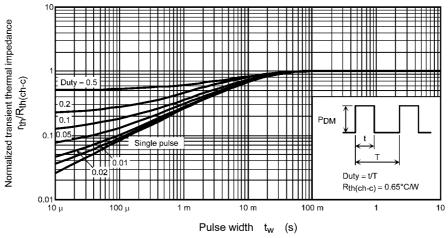


Fig. 8.12  $r_{th}/R_{th(ch-c)} - t_w$  (Guaranteed Maximum)

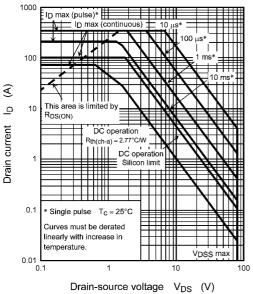


Fig. 8.13 Safe Operating Area (Guaranteed Maximum)

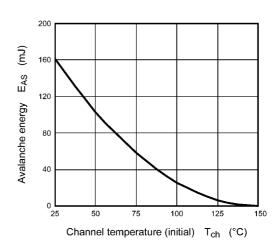


Fig. 8.14 E<sub>AS</sub> - T<sub>ch</sub> (Guaranteed Maximum)

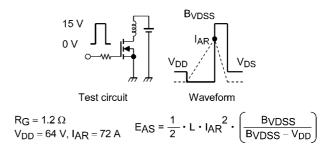


Fig. 8.15 Test Circuit/Waveform

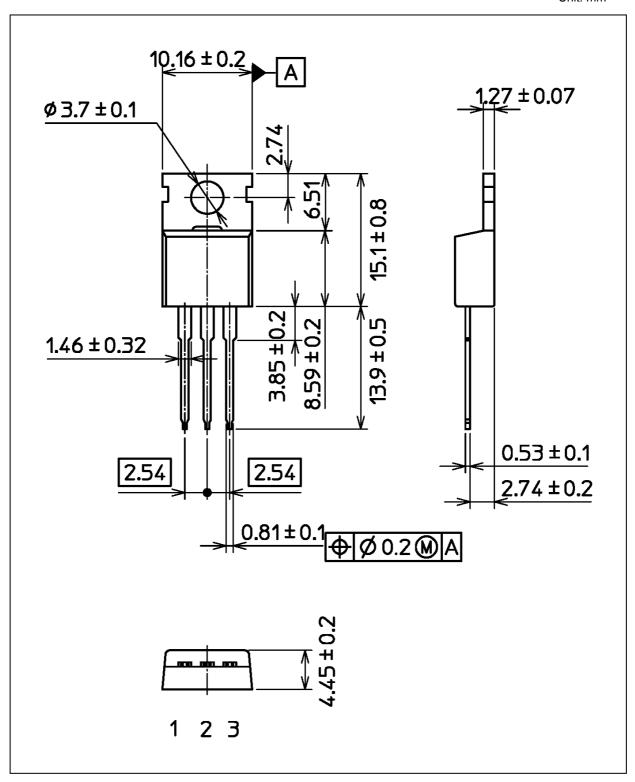
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Rev.1.0



## **Package Dimensions**

Unit: mm



Weight: 1.93 g (typ.)

|                  | Package Name(s) |
|------------------|-----------------|
| TOSHIBA: 2-10X1A |                 |
| Nickname: TO-220 |                 |



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